



566.39787CX1

#18/B
MA
5/12/03

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): T. UCHIDA, et al.
Serial No.: 09/976,001
Filed: October 15, 2001
For: ABRASIVE LIQUID FOR METAL AND METHOD
OF POLISHING
Group: 1765
Examiner: L. Umez-Eronini

RECEIVED
MAY 09 2003
GROUP 1700

AMENDMENT

Assistant Commissioner of Patents
Washington, D.C. 20231

May 7, 2003

Sir:

In response to the Office Action mailed February 7, 2003, please amend the above-identified application as follows:

IN THE SPECIFICATION:

Please delete the paragraph on page 13, lines 4-17, and substitute therefor the following new paragraph:

B1 --The metal-oxidizing agent may include hydrogen peroxide (H₂O₂), nitric acid, potassium periodate, hypochlorous acid, ozone water, and the like. In the case when the substrate is a silicon substrate having devices for integrated circuits, any contamination due to alkali metals, alkaline earth metals or halides is not desirable,